Build Up HDI (Standard)

HDI04_1+2b+1_1,40_engl

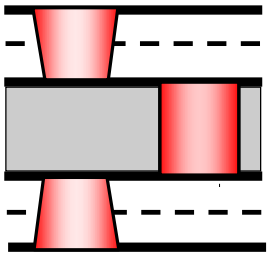
4 - Layers

Core: 1,20 mm Cu 35/35 µm

WE-Articel No.: | **1 + 2B + 1**

Customer:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	60	
	2			12 µm		35	
			1,200 mm			1200	
	3			12 µm		35	
					1 x 1080	60	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1414

Note: Lamination thickness for Prepregs depending on layout characteristics.

							Date:	Engineer:
final lamination thickness:	**1,40**	+/-	0,11	mm				
thickness with electro plated Cu:	1,49	+/-	0,14	mm				
total thickness with soldermask	1,55	+/-	0,16	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision	page:
04.01.2006	**S. Keller**	04.05.2006	M.Kress	04.01.2006	R. Schönholz	00	5+